



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Fall Meeting 2022

September 2nd 13:00-17:00 (JST)

via OVTCCM

TC Chapter Announcements

Next TC Chapter Meeting

Thursday, December 15, 2022, 13:30-16:30 [JST] @ Tokyo Big Sight (via OVTCCM) Hybrid

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Yasuhisa Ito (MURATA MACHINERY), Tsuyoshi Nagashima (Miraial Co., Ltd.), Daisuke Sado (DAIHEN Corporation)

SEMI Staff: Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
DAIFUKU	Suzuki	Tomoko	<i>Rorze</i>	<i>Yokoyama</i>	<i>Koji</i>
Acteon NEXT	Komatsu	Shoji	TOKYO SEIMITSU	Taniguchi	Naomune
<i>Marubeni Plax</i>	<i>Igeta</i>	<i>Luke</i>	JEOL	Asayama	Kyoichiro
<i>Panasonic</i>	<i>Shieh</i>	<i>Yau De</i>	TEL	Mashiro	Supika
SCREEN Semiconductor Solutions	Nishimura	Takayuki	<i>DAIFUKU</i>	<i>Nishibayashi</i>	<i>Yoshitaka</i>
Shin-Etsu Polymer Co., Ltd.	Shida	Hiroyuki	<i>DISCO Corporation</i>	<i>Kobinata</i>	<i>Kyosuke</i>
Miraial Co., Ltd.	Nagashima	Tsuyoshi	Shin-Etsu Polymer Co., Ltd.	Odashima	Satoshi
MURATA MACHINERY	Ito	Yasuhisa	SEMI Japan	Nakajo	Mami
DAIHEN	Sado	Daisuke			

Table 2 Leadership Changes

None

Table 3 Committee Structure Changes

None

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6898	Revision to SEMI E181, - SPECIFICATION FOR PANEL FOUF FOR PANEL LEVEL PACKAGING	Passed, as ballot
6899	Revision to SEMI E181.1, - Specification for Panel FOUF for 510 to 515 mm Panel Size and 12 Slots	Passed, as ballot
6900	Revision to SEMI E181.2, - Specification for Panel FOUF for 510 to 515 mm Panel Size and 6 Slots	Passed, as ballot
6901	Revision to SEMI E181.3, - Specification for Panel FOUF for 600 to 600 mm Panel Size and 12 Slots	Passed, as ballot



Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6902	Revision to SEMI E181.4, - Specification for Panel FOUP for 600 to 600 mm Panel Size and 6 Slots	Passed, as ballot

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

None

Table 6 Authorized Activities

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Ballots

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 8 SNARF(s) Granted a One-Year Extension

None

Table 9 SNARF(s) Abolished

None

Table 10 Standard(s) to receive Inactive Status

<i>Standard Designation</i>	<i>Title</i>
None	

Table 11 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20220902-01	SEMI Staff	To submit A&R forms of 6898,6899,6900,6901 & 6902 to ISC A&R

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20220527-01	Global PIC Standards Maintenance TF	To prepare SNARF for Reapproval of SEMI E84-1109 (Reapproved 1217), Specification for Enhanced Carrier Handoff Parallel I/O Interface > Open



1 Welcome, Reminders, and Introductions

Yasuhisa Ito (MURATA MACHINERY) called the meeting to order at 13:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01-02_Required Element Nov 2020 Rev1_E+J_r1

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the previous meeting minutes of the PIC Japan TC Chapter on December 17,2021 as written.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEMITSU CO., LTD.)
Discussion:	None
Vote:	11 in favor and 0 opposed. Motion Passed.

Attachment: 02-01_PIC Mins_0527_2022v1.1

3 Liaison Reports

3.1 PIC North America TC Chapter

Mami Nakajo (SEMI) gave the report based on the materials.

Attachment: 03-01_NA PIC Liaison Report July2022 v2

4 SEMI Staff Report

Mami Nakajo (SEMI) gave the SEMI Staff Report. based on the materials.

Kyoichiro Asayama (JEOL) and Tsuyoshi Onishi, Hitachi High-Tech were awarded SEMI International Standards Excellence Award, presented since 1992, the Excellence Award this year honored the following leadership team of the Electron Microscopy Workflow Task Force including the primary task force leaders, document author, and SEMI Japan task force leaders at SEMICON West 2022 Hybrid.

- Richard Young, Thermo Fisher Scientific
- Laurens Kwakman, Consultant, formerly of Thermo Fisher Scientific
- Peter Wagner, Consultant
- Kyoichiro Asayama, JEOL
- Tsuyoshi Onishi, Hitachi High-Tech

Attachment: 04-01_Staff Report July 2022 v6_J

5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

5.1 Cycle 4-2022 submitted by the Japan TC Chapter

5.1.1 Doc6898, Revision to SEMI E181, - SPECIFICATION FOR PANEL FOUN FOR PANEL LEVEL PACKAGING



Motion:	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (Regulations ¶ 8.7.1)
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Attachment: #6898_BallotReport_E181_final

5.1.2 Doc6899, Document Title: Revision to SEMI E181.1-0222: SPECIFICATION FOR PANEL FOUF FOR 510 TO 515 MM PANEL SIZE AND 12 SLOTS

Motion:	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (Regulations ¶ 8.7.1)
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Attachment: #6899_BallotReport_E181.1_final

5.1.3 Doc6900, Revision to SEMI E181.2-0222: SPECIFICATION FOR PANEL FOUF FOR 510 TO 515 MM PANEL SIZE AND 6 SLOTS

Motion:	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (Regulations ¶ 8.7.1)
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Attachment: #6900_BallotReport_E181.2_final

5.1.4 Doc6901, Revision to SEMI E181.3-0222: SPECIFICATION FOR PANEL FOUP FOR 600 TO 600 MM PANEL SIZE AND 12SLOTS

Motion:	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (Regulations ¶ 8.7.1)
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	13 in favor and 0 opposed. Motion Passed.

Attachment: #6901_BallotReport_E181.3_final

5.1.5 Doc6902, Revision to SEMI E181.4-0222: SPECIFICATION FOR PANEL FOUP FOR 600 TO 600 MM PANEL SIZE AND 6SLOTS

Motion:	This is not a Safety Document, when all safety-related information is removed, the Document is still technically sound and complete. (Regulations ¶ 8.7.1)
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	13 in favor and 0 opposed. Motion Passed.

Motion:	This Document passed TC Chapter review as balloted and will be forwarded to the ISC A&R SC for procedural review.
By / 2nd:	Shoji Komatsu (Acteon NEXT) / Naomune Taniguchi (TOKYO SEIMITSU CO., LTD)
Discussion:	None
Vote:	14 in favor and 0 opposed. Motion Passed.

Attachment: #6902_BallotReport_E1814_final

6 Subcommittee and Task Force Reports

6.1 300 mm Tape Frame PI&C TF

Naomune Taniguchi (TOKYO SEIMITSU CO., LTD) reported for the task force. Of note:

The TF is considering that the TF will be disbanded at the next committee meeting once Document #6895, Line Item Revision to SEMI E185-1221 Specification for 300mm Tape Frame FOUP will be published.

Attachment: 06-01_20220902_300mm Tape Frame PIC TF_ActivityReports

6.2 Global PIC Standards Maintenance TF

Shoji Komatsu (Acteon NEXT) reported for the task force. Of note:

- 6.2.1 SEMI E92-0302E: Specification for 300 mm Light Weight and Compact Box Opener/Loader To Tool-Interoperability Standard (Bolts/Light)
→Cycle 6-2022 submitted by the Japan TC Chapter.

- 6.2.2 SEMI E84-1109 (Reapproved 1217): Specification for Enhanced Carrier Handoff Parallel I/O Interface
→The TF will prepare SNARF for the reapproval this Standard.
Korea members pointed out that E15.1 and E131 are in conflict and Japan and NA are discussing how to deal with this.
Supika Mashiro(TEL) said that it is possible to make the Inactive Standard Active, but there is no other way but add it in the Auxiliary Information to avoid conflicts.

6.3 Japan Electron Microscopy Workflow liaison TF

Kyoichiro Asayama (JEOL) reported for the task force as attached slides.

Attachment: 06-03_220902PI&CTC

6.4 Panel Level Packaging Panel FOUP TF

Shoji Komatsu (Acteon NEXT) reported for the task force as attached slides.

Attachment: 06-04_Panel FOUP TF report_20220902A

6.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

No update

6.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

Mami Nakajo (SEMI) reported for the task force. Of note:

There is no update since NA 3DP&I haven't met since December 8th,2021.

7 Old Business

7.1 Project Period Review – None

7.2 5 years review

7.2.1 SEMI E84-1109 (Reapproved 1217): Specification for Enhanced Carrier Handoff Parallel I/O Interface

→Postponed.

8 New Business

8.1 Report of New Activity

8.1.1 SNARF Proposal for Reapproval of SEMI E84-1109 (Reapproved 1217) - Specification for Enhanced Carrier Handoff Parallel I/O Interface

→Postponed.

8.1.2 Liaison of E72 Revision TF

Supika Mashiro(TEL) suggested that E72 Revision TF is active in NA. If there was a Liaison TF in Japan, would it be easier to participate?

Yasuhisa Ito (MURATA MACHINERY) said currently it is possible to participate in the NA TF, so for now, please join the NA TF directly.

9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20220527-01	Global PIC Standards Maintenance TF	To prepare SNARF for Reapproval of SEMI E84-1109 (Reapproved 1217), Specification for Enhanced Carrier Handoff Parallel I/O Interface > Open

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20220527-01	Global PIC Standards Maintenance TF	To prepare SNARF for Reapproval of SEMI E84-1109 (Reapproved 1217), Specification for Enhanced Carrier Handoff Parallel I/O Interface

10 Next Meeting and Adjournment

The next committee meeting is scheduled for Thursday, December 15, 2022, 13:30-16:30 [JST] @ Tokyo Big Sight, Tokyo (via OVTCCM) Hybrid in conjunction with the SEMICON Japan.

With regard to TF meetings, Global PIC Standards Maintenance TF and Global PIC Standards Maintenance TF will be held on the same day from 9am to 11 am and Japan Electron Microscopy Workflow liaison TF is not scheduled to take place in conjunction with the SEMICON Japan.

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 16:30

Respectfully submitted by:

Mami Nakajo
Standards & EHS
SEMI Japan
Phone: 81.3.3222.5949
Email: mnakajo@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Mirai), Co-chair	September 28, 2022
Daisuke Sado (Daihen), Co-chair	September 27, 2022
Ito Yasuhisa (Murata Machinery), Co-chair	September 28, 2022

Table 13 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2020 Rev1_E+J_r1	#6900_BallotReport_E181.2_final
02-01_PIC Mins_0527_2022v1.1	#6901_BallotReport_E181.3_final
03-01_NA PIC Liaison Report July2022 v2	#6902_BallotReport_E1814_final
04-01_Staff Report July 2022 v6_J	06-01_20220902_300mm Tape Frame PIC TF_ActivityReports
#6898_BallotReport_E181_final	06-03_220902PI&CTC
#6899_BallotReport_E181.1_final	06-04_Panel FOUP TF report_20220902A



#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.